Solder Void Impact on Power Module Thermal Resistance using Transient Thermal Analysis

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# Summary

This research utilizes a customized thermal transient analysis method for the purpose of identifying the thermal impact of solder voids in power modules. At present, most of the existing experimental transient thermal analysis techniques focus on developing a 1-dimensional Cauer network thermal model. However, this model neglects to consider the effects of heat spreading, which is a highly relevant effect when considering heat flow through the solder layer. Because of this, models based upon a 1-D assumption of heat flow have been shown to have significant error when compared to a 3-D finite element simulation1.[1]

In order to address this issue, the research presented here utilizes an adapted interpretation of the time constant spectrum technique2[2]as well as through a derivative deviation method3.[3]These methods are used to analyze experimental data of the thermal resistance of sample modules consisting of a single diode. Both of the methods are applicable to a 3-D heat flow model, which includes the effects of thermal spreading.

# Motivation

In the continual effort to improve the thermal performance of modern power modules, manufacturers have placed a heavy emphasis on the removal of voids in the chip-attach solder layer. However, void reduction procedures often involve a vacuum or pressurized soldering oven, thus increasing the cost of production. Therefore, it is important to gain an accurate understanding of how voids impact the thermal performance of power modules in order to give insight into the optimal level of investment that should be placed into void reduction equipment. This is particularly useful in situations where cost is a significant constraint.

# Results

The chip is a 600V/50A power diode, and it was soldered to an aluminum clad PCB with SAC 305 solder, and then wirebonded using eight 250 μm wire bonds. The first piece of data collected were X-ray images of the solder layers of each module, which were subsequently processed and the void content of each was calculated (Fig. 1). Next, thermal data was collected by monitoring the temperature of the modules over time as a 24A heating current was applied over 120 seconds. The temperature was monitored using the forward voltage of the diode at 50 mA, and the first 200 μs of data was replaced with an estimation that the actual temperature decreases linearly with the square root of time during this period. This was used to generate the time constant spectrum, and the peaks were located using a custom script. Peaks in the time constant spectrum roughly correspond to points in time where the heat flux reaches a layer with higher thermal resistance. The first peak in Figure 2 corresponds to the thermal response of the solder layer. Notably, the heat flux does not pass through a layer uniformly as would be the case in 1-D heat flow, which can be seen by the fact that the peaks are not sharp points but are rounded in nature.

In addition, the graph of the deviation of in Figure 3 shows that the thermal resistance of the modules begins to deviate near the 1-2 ms mark, which agrees with the location of the first peak in Figure 2. This deviation is due to the differing thermal resistances of the solder layers between each module, and so the total difference can be measured by sampling a point in time near 10 ms (dotted blue line in Fig. 3), where the curves re-converge.

The measurement at 10 ms shows a strong correlation between thermal resistance and void count (Fig. 4). This relationship is much stronger than the correlation at steady-state (Fig 4.). This serves as an indicator that the transient method allowed the isolation of the solder layer from unwanted variance.

**Figures**

A graph with blue dots and numbers

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Fig. 6: Correlation between voids and thermal resistance at 112 sec

Fig. 5: Test module construction

Fig. 4: Correlation between voids and thermal resistance at 10 ms

Fig. 3: Graph of of each sample, filtered and normalized with respect to the average of across all samples

Fig. 2: Time constant spectrum with peaks identified

Fig. 1: Raw X-ray image of solder layer (left) and processed image (right)